Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138							
PRODUCT/PROCESS CHANGE NOTICE (PCN)							
PCN #: A1901-01 Date: January 31, 20 Product Affected: 71256SA35SOG1 71256SA35SOG18	 MEANS OF DISTINGUISHING CHANGED DEVICES: Product Mark Back Mark Lot # will have a "MM" prefix Date Code 						
Date Effective: April 30, 2019	□ Other						
Contact: IDT PCN DESK	Attachment: Yes No						
E-mail: pcndesk@idt.com	Samples: Please contact your local sales representative for sample request & availability.						
DESCRIPTION AND PURPOSE OF CHANGE: Die Technology This notification is to advise our customers that IDT is transferring product currently assembled at Amkor Philippines (ATP) to Carsem, Malaysia as a result of ATP Assembly Process discontinue the assembly process on the automotive products. Equipment There is no change to the moisture performance rating. Testing Please refer to Attachment 1 for the qualification summary and material set details. Data Sheet Other RELIABILITY/QUALIFICATION SUMMARY: Qualification has been successfully completed. There is no change in MSL rating. CUSTOMER ACKNOWLEDGMENT OF RECEIPT: IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable. IDT reserves the right to ship either version manufactured after the process change effective date until the inventory							
Customer:	Approval for shipments prior to effective date.						
Name/Date: E-Ma	ail Address:						
Title: Phone	e# /Fax# :						
CUSTOMER COMMENTS:							
IDT ACKNOWLEDGMENT OF RECEIPT: RECD. BY:	DATE						



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ATTACHMENT 1 - PCN # : A1901-01

PCN Type: Change Assembly Location

Data Sheet Change: N/A

Detail Of Change:

This notification is to advise our customers that IDT is transferring product currently assembled at Amkor Philippines (ATP) to Carsem, Malaysia as a result of ATP discontinue the assembly process on the automotive products.

The material set details of the current and new Assembly locations is shown in the tables below. The die attach, mold compound and bonding wire used at the new assembly site are qualified IDT materials. There is no change from the existing qualified lead frame material and lead finish for this alternate assembly site.

There is no change to the moisture performance rating.

	Existing	New	
Material Set / Assembly	ATP - Amkor, Philippines	CRSM - Carsem Malaysia	
Die Attach	Ablestik 8290	Ablestik 8290	
Bonding Wire	1.3 mils Gold Wire	1.3 mils Gold Wire	
Mold Compound	G600	G700HA	
Lead Finish	100% Sn	100% Sn	

Qualified Material Sets, by Assembly Subcontractor



Package Qualification Test Report SOIC

Packages CoveredSOIC 28Assembly LocationCarsemReport DateJanuary 24, 2019

Qual Vehicle Information

	Lot 1	Lot 2	Lot 3	
Package Type	SOIC 28	SOIC 28	SOIC 28	
Package Dimension	17.9 x 7.6 x 2.34mm	17.9 x 7.6 x 2.34 mm	17.9 x 7.6 x 2.34 mm	
Lead Pitch	1.27mm	1.27mm	1.27mm	
Lead Frame Material	C194	C194	C194	
Die Attach Material	Ablestik 8290	Ablestik 8290	Ablestik 8290	
Wire Bond Material	1.3mil Au	1.3mil Au	1.3mil Au	
Mold Compound Material	Sumitomo G700HA	Sumitomo G700HA	Sumitomo G700HA	
Plating Finish	100% Sn, Matte	100% Sn, Matte	100% Sn, Matte	

Qualification Test and Results (Reference AEC-Q100)

		Sample Size/Reject		
		SOIC 28		
Stress Tests	Reference Spec / Conditions	Lot 1	Lot 2	lot 3
High Temperature Operating Life (HTOL)	JESD22-A108, JESD85 / Vcc=6.0V, Ta=125°C, 1000 hours	77/0	77/0	77/0
Early Life Failure Rate (ELFR)	JESD22-A108 / JESD74 / Vcc=6.0V, Ta=125°C, 48 hours	800/0	800/0	800/0
High Temperature Storage Test (HTSL)	JESD22-A103 / 150 °C, 1000 hours	45/0	-	-
Temperature Humidity Bias* (HAST)	JESD22-A110 / 130 °C, 85% RH, Vccmax, 96 hours	77/0	77/0	77/0
Temperature Cycling* (TC)	JESD22-A104 / . 55 °C to +125 °C, 1000 cycles	77/0	77/0	77/0
Moisture Sensitivity Level, MSL	IPC/JEDEC J-STD-20, MSL 3, 260 °C	25/0	25/0	-
Wire Bond Pull (WBP)	MIL883 M2011 / Pre-stress	5/0	5/0	5/0
	Post PC + 1000cyc TC	5/0	5/0	5/0
Wire Bond Shear (WBS)	AEC Q100-001	5/0	5/0	5/0
Solderbility test (SD)	MIL-STD-883 (Method 2003), J-STD-002D, solder bath SAC 245°C	15/0	-	-
Physical Dimension (PD)	JESD22-B100 (Per applicable IDT Package Outline Drawing)	10/0	10/0	10/0

* Preconditioning sequence according to JESD22-A113 prior to stress test.